

FIG. 1

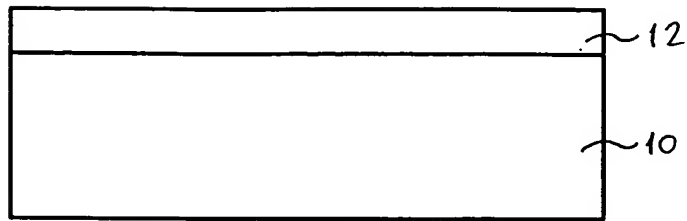


FIG. 2

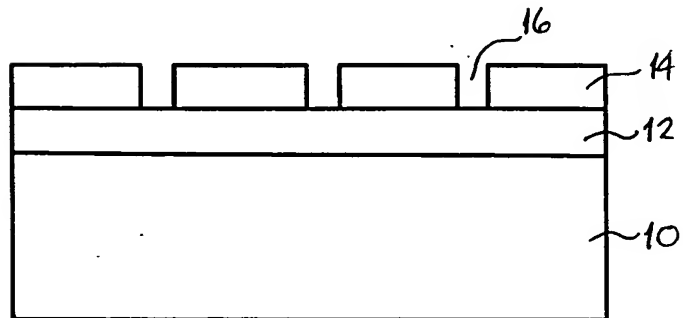


FIG. 3

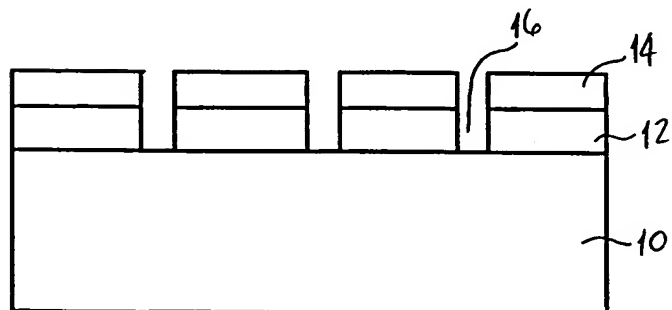


FIG. 4

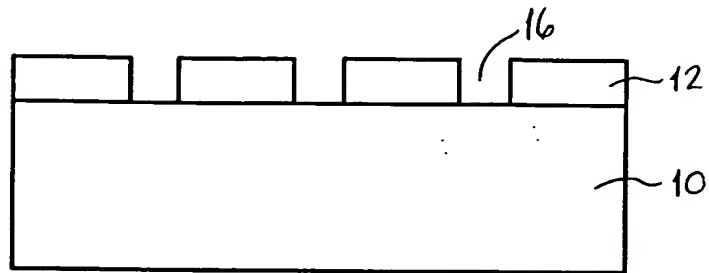


FIG. 5

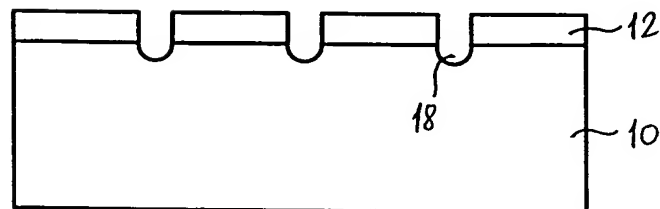


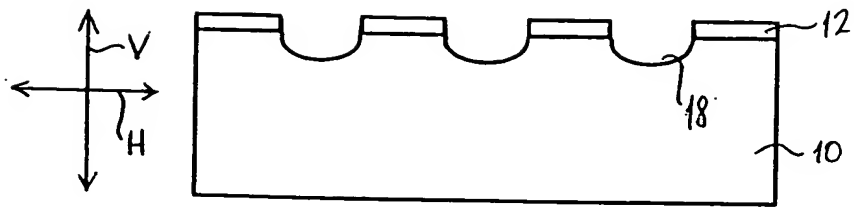
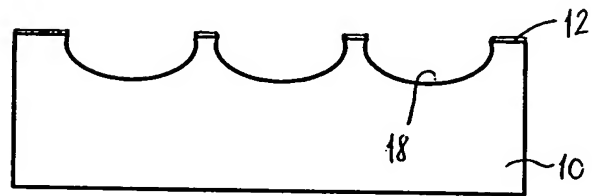
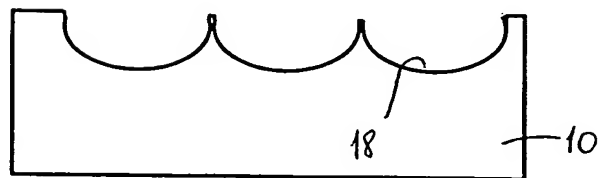
FIG. 6A**FIG. 6B****FIG. 6C**

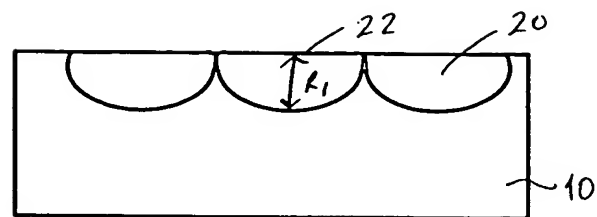
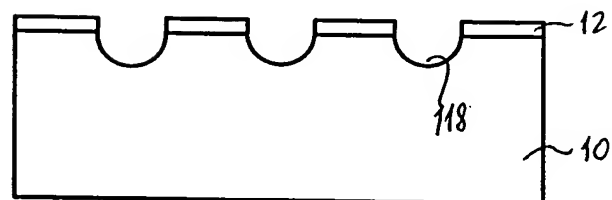
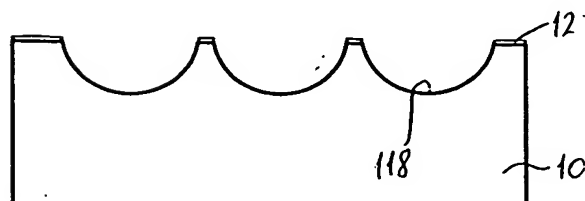
FIG. 6D**FIG. 7A****FIG. 7B**

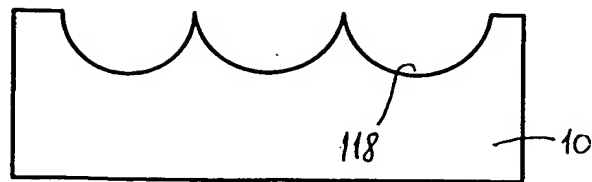
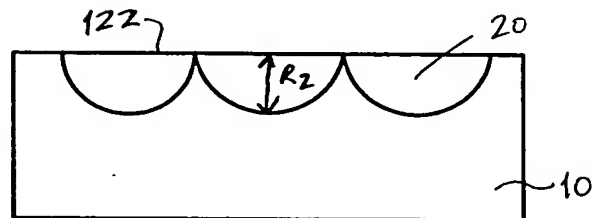
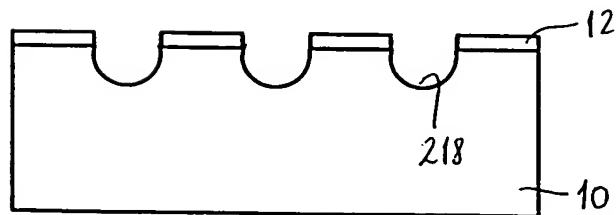
FIG. 7C**FIG. 7D****FIG. 8A**

FIG. 8I Title: METHOD OF FORMING MICRO-LENSES

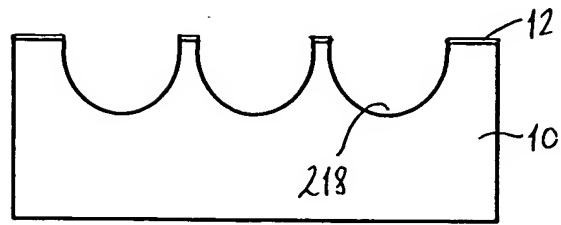


FIG. 8C

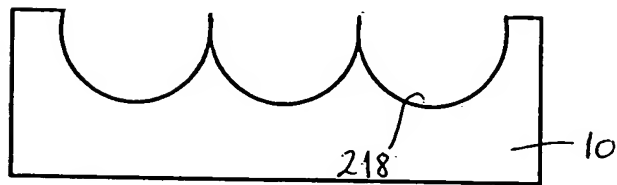


FIG. 8D

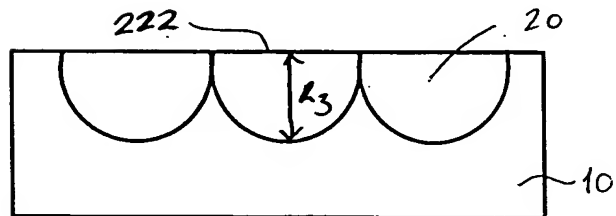


FIG. 9A

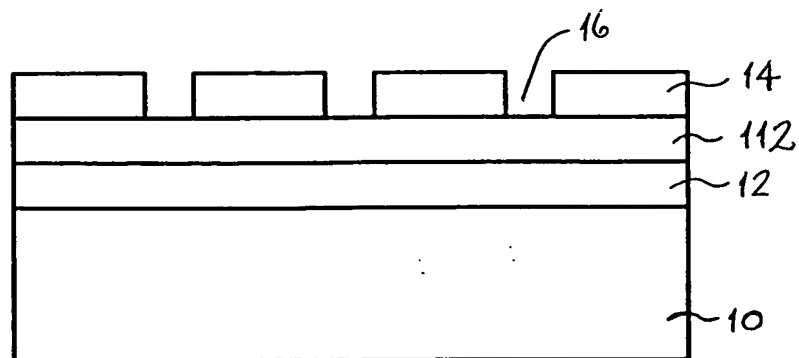


FIG. 9B

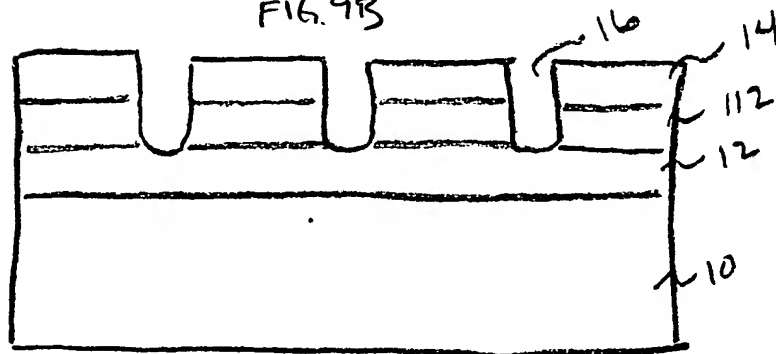


FIG. 9C

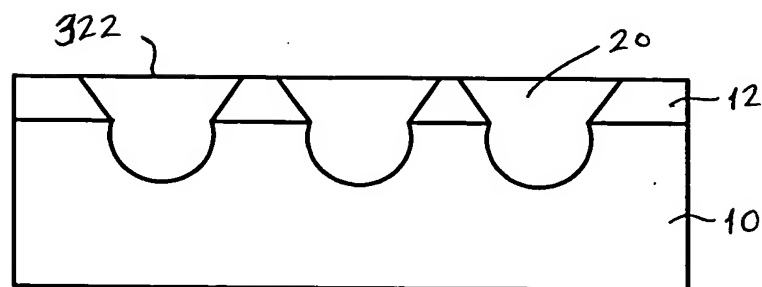


FIG. 10

Etch rates in Angstroms/minute

MATERIAL	WET ETCHANT			
	BOE 20:1	HF 10:1	HF 100:1	HF 25:1
DARC Fuse Annealed	1012	-----	33	132
BPSG (2.7/7.2) WJ RTP & Anneal	362	-----	242	992
BPSG (3.0/6.0) WJ As Deposited	700	10100	860	3440
BPSG (3.0/6.0) WJ RTP & Anneal	297	2190	210	840
BPSG (3.0/7.6) Centura Densified	480	278	1130	68
BPSG (3.8/6.9) WJ RTP & Anneal	250	2200	860	223
PSG (6.9) As Deposited	1240	-----	708	4350
HDP CVD Oxide As Deposited	401	444	39	141.9
HDP CVD Oxide Densified	366	312	32	118.7
Low Silane PECVD	690	1080	118	472
TEOS PECVD	540	632	62	248
TEOS PECVD Densified	390	293	28	111